



## Materials Declaration Form


<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-06-10
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

<b>Uncertainty Statement</b>	
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<b>Legal Statement</b>	
<b>Supplier Acceptance *</b>	true <b>Legal Declaration *</b> Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L072RZI6	P12I*447XXXZ	A	9996	2017-06-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	27.30	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	5,5,0.6	64	No lead	
Comment	Package : A019 UFBGA 5X5X0.6 64L P 0.5 MM 8526322			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	P121*447XXXZ				6999999.0	1000000.0				
note : Substance present with less 0.001mg will not be declared in this document																
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.221	mg	supplier	die	Silicon (Si)	7440-21-3		1.916	mg	862574	70183				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	12157	989				
				supplier	metallization	Copper (Cu)	7440-50-8		0.088	mg	39622	3223				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.010	mg	4502	366				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	5853	476				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	450	37				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.024	mg	10806	879				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.142	mg	63935	5201				
				SILICON DIE	M-011 Other inorganic materials	1.916	mg	supplier	DIE	Silicon (Si)	7440-21-3		1.916	mg	1000000	70171
				SUBSTRATE (E679FGB)	M-011 Other inorganic materials	7.906	mg	supplier	CORE	Glass Cloth	65997-17-3		0.364	mg	46000	13322
supplier	CORE	Silica vitreous	60676-86-0						0.040	mg	5000	1448				
supplier	CORE	Thermosetting resin	Proprietary						0.103	mg	13000	3765				
supplier	CORE	Copper foil	7440-50-8						0.826	mg	104500	30264				
supplier	SOLDERMASK (AUS308)	Talc containing no asbestiform fibers	14807-96-6						0.142	mg	18000	5213				
supplier	SOLDERMASK (AUS308)	Barium sulfate	7727-43-7						0.277	mg	35000	10136				
supplier	SOLDERMASK (AUS308)	Dipropylene monomethyl ether	34590-94-8						0.134	mg	17000	4923				
supplier	SOLDERMASK (AUS308)	Napthalene	91-20-3						0.012	mg	1500	434				
supplier	SOLDERMASK (AUS308)	Morpholine derivative	Proprietary						0.040	mg	5000	1448				
supplier	CU PLATING	Copper (Cu)	7440-50-8						4.151	mg	525000	152043				
DIE ATTACH (ATB-130U)	M-011 Other inorganic materials	0.284	mg	supplier	NI PLATING	Nickel (Ni)	7440-02-0		1.581	mg	200000	57921				
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.237	mg	30000	8688				
				supplier	GLUE	Butadiene,acrylonitrile,polymer,carboxy-termi	68610-41-3		0.199	mg	700000	7285				
				supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4		0.028	mg	100000	1041				
				supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4		0.026	mg	92000	957				
				supplier	GLUE	Dapsone	80-08-0		0.028	mg	97000	1009				
				supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin	25068-38-6		0.003	mg	10000	104				
				supplier	GLUE	4,4, isopropylidenediphenol	80-05-7		0.000	mg	1000	10				
				BONDING WIRE (MKE 4N)	M-011 Other inorganic materials	0.280	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.280	mg	1000000	10248
				SOLDERBALL (Sn96.5Ag3.5)	M-011 Other inorganic materials	1.987	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		1.918	mg	965000	70247
supplier	SOLDERBALL	Silver (Ag)	7440-22-4						0.070	mg	35000	2548				
ENCAPSULATION (GE-100LFC5)	M-011 Other inorganic materials	12.706	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		11.213	mg	900000	410743				
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		0.672	mg	45000	24605				
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		0.597	mg	40000	21871				
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		0.149	mg	10000	5468				
supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.075	mg	5000	2734								